Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An exposure apparatus which exposes a substrate by radiating an exposure light beam onto the substrate through a liquid, the exposure apparatus comprising:

a supply inlet from which the liquid is supplied, the liquid supplied from the supply inlet covering only a portion of an upper surface of the substrate during exposure;

a substrate stage which has having a substrate-holding member for holding by which the substrate is held, and which is movable; the substrate-holding member holding the substrate on an underside of the substrate and the substrate-holding member being movable below the supply inlet; and

a temperature adjustment system which performs temperature adjustment for the substrate-holding member depending on a temperature of the liquid to be supplied <u>from</u> the supply inlet onto the substrate held by the substrate-holding member.

- 2. (Original) The exposure apparatus according to claim 1, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that heat transfer is reduced between the substrate and the liquid on the substrate.
- 3. (Original) The exposure apparatus according to claim 1, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that no temperature change of the liquid is caused by contact between the liquid and the substrate.
- 4. (Original) The exposure apparatus according to claim 3, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that no temperature distribution is generated in the liquid.

- 5. (Original) The exposure apparatus according to claim 3, further comprising a surface position-detecting unit which detects surface position information about a surface of the substrate by emitting a detecting light beam onto the substrate through the liquid and receiving a reflected light beam from the substrate through the liquid, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member to suppress measurement error of the surface position-detecting unit due to the temperature change of the liquid.
- 6. (Original) The exposure apparatus according to claim 1, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that no temperature change of the substrate is caused by contact between the liquid and the substrate.
- 7. (Previously Presented) The exposure apparatus according to claim 6, further comprising a mark-detecting system which detects an alignment mark on the substrate not through the liquid, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that no temperature change of the substrate is caused by the contact between the liquid and the substrate after detecting the mark by the mark-detecting system.
- 8. (Currently Amended) The exposure apparatus according to claim 1, wherein the temperature adjustment system uses a liquid which is <u>the</u> same as the liquid to be supplied onto the substrate to perform the temperature adjustment for the substrate-holding member.
 - 9. (Canceled)
- 10. (Original) The exposure apparatus according to claim 1, further comprising a temperature sensor which measures a temperature of the substrate-holding member.

11-29. (Canceled)

30. (Currently Amended) An exposure apparatus which exposes a <u>first or a second</u> substrate by radiating an exposure light beam onto the <u>first or second</u> substrate through a liquid, the exposure apparatus comprising:

a liquid supply system having a supply inlet from which the liquid is supplied;
a first substrate stage which has having a first substrate-holding member for
holding the by which the first substrate and which is movable; is held, the first substrateholding member holding the first substrate on an underside of the first substrate and the first
substrate-holding member being movable below the supply inlet;

a second substrate stage which has having a second substrate-holding member for holding the by which the second substrate and which is movable; is held, the second substrate-holding member holding the second substrate on an underside of the second substrate and the second substrate-holding member being movable below the supply inlet;

a measuring station which performs measurement for <u>one of</u> the substrate <u>substrates</u> held by one of the stages;

an exposure station which performs exposure for the substrate held by the other of the stages, the exposure station being provided with a-the liquid supply system which supplies the liquid onto the substrate; substrate held by the other of the stages, the supplied liquid covering only a portion of an upper surface of the substrate held by the other of the stages during the exposure; and

temperature adjustment systems which are provided for the first substrate stage and the second substrate stage respectively and which perform temperature adjustment for the substrate-holding member of each of the stages depending on a temperature of the liquid to be supplied from the liquid supply system.

- 31. (Original) The exposure apparatus according to claim 30, wherein the measurement for the substrate in the measuring station includes measurement of surface position information about a surface of the substrate.
- 32. (Original) The exposure apparatus according to claim 30, wherein the measurement for the substrate in the measuring station includes detection of an alignment mark on the substrate.
- 33. (Currently Amended) The exposure apparatus according to claim 30, wherein the temperature adjustment system performs the temperature adjustment for the <u>first</u> substrate-holding member before performing the measurement for the <u>substrate</u>. <u>first substrate</u> and performs the temperature adjustment for the second substrate-holding member before performing the measurement for the second substrate.
 - 34. (Canceled)
- 35. (Currently Amended) The exposure apparatus according to claim 30, wherein the temperature adjustment system performs, after the measurement for the substrate in the measuring station, the temperature adjustment for the <u>respective</u> substrate-holding member to suppress temperature change of the <u>substrate</u> substrate in the measuring station.
 - 36-43. (Canceled)
 - 44. (Previously Presented) A method for producing a device, comprising:

 exposing a substrate using the exposure apparatus as defined in claim 1; and
 processing the exposed substrate.
 - 45-64. (Canceled)
- 65. (Currently Amended) The exposure apparatus according to claim 30, further comprising a projection optical system which projects an image of a pattern through the liquid onto the substrate through the liquid. being exposed, wherein the exposure station is provided with the projection optical system.

- 66-67. (Canceled)
- 68. (Previously Presented) A method for producing a device, comprising:

 exposing a substrate using the exposure apparatus as defined in claim 30; and
 processing the exposed substrate.
- 69. (Canceled)
- 70. (Previously Presented) The exposure apparatus according to claim 1, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that the temperature of the substrate-holding member is the same as the temperature of the liquid to be supplied onto the substrate held by the substrate-holding member.
- 71. (Previously Presented) The exposure apparatus according to claim 1, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that no deformation of the substrate is caused by contact between the liquid and the substrate.
- 72. (Currently Amended) The exposure apparatus according to claim 10, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that the measured temperature of the substrate-holding member is the same as the temperature of the liquid to be supplied onto the substrate held by the substrate-holding member.
 - 73. (Canceled)
- 74. (Currently Amended) An exposure method comprising:

 holding a substrate by a substrate-holding member;member on an underside of

 the substrate;

supplying a liquid from a supply inlet onto an upper surface of the substrate held by the substrate-holding member so that the supplied liquid covers only a portion of a-the upper surface of the substrate held by the substrate-holding member;

controlling a temperature of the substrate-holding member depending on a temperature of the liquid to be supplied onto the substrate held by the substrate-holding member; and

moving the substrate below the supply inlet; and

exposing the substrate by radiating an exposure light beam onto the substrate through the supplied liquid.

- 75. (Previously Presented) The exposure method according to claim 74, wherein the temperature of the substrate-holding member is controlled so that heat transfer between the substrate and the supplied liquid is prevented.
- 76. (Previously Presented) The exposure method according to claim 74, wherein the temperature of the substrate-holding member is controlled so that temperature change of the liquid on the substrate is prevented.
- 77. (Previously Presented) The exposure method according to claim 74, wherein the temperature of the substrate-holding member is controlled so that temperature change of the substrate due to contact between the supplied liquid and the substrate is prevented.
- 78. (Previously Presented) The exposure method according to claim 77, further comprising detecting an alignment mark on the substrate held by the substrate-holding member not through the liquid, wherein the temperature of the substrate-holding member is controlled so that the temperature change of the substrate caused after detecting the mark is prevented.
- 79. (Currently Amended) The exposure method according to claim 74, wherein the temperature of the substrate-holding member is controlled using a liquid which is the same as the liquid to be supplied onto the substrate.

- 80. (Previously Presented) The exposure method according to claim 79, wherein the temperature of the substrate-holding member is controlled by flowing the liquid in the substrate-holding member.
- 81. (Previously Presented) The exposure method according to claim 74, further comprising measuring the temperature of the substrate-holding member, wherein the temperature of the substrate-holding member is controlled so that the measured temperature of the substrate-holding member is the same as the temperature of the liquid to be supplied onto the substrate held by the substrate-holding member.
- 82. (Previously Presented) The exposure method according to claim 74, wherein the temperature of the substrate-holding member is controlled so that the temperature of the substrate-holding member is the same as the temperature of the liquid to be supplied onto the substrate held by the substrate-holding member.
- 83. (Previously Presented) The exposure method according to claim 74, wherein the temperature of the substrate-holding member is controlled so that deformation of the substrate due to contact between the supplied liquid and the substrate is prevented.
- 84. (New) An exposure apparatus which exposes a substrate by radiating an exposure light beam onto the substrate through a liquid, the exposure apparatus comprising:

a supply inlet from which the liquid is supplied, the liquid supplied from the supply inlet covering only a portion of an upper surface of the substrate during exposure;

a substrate stage having a substrate-holding member by which the substrate is held, the substrate holding member holding the substrate on an underside of the substrate and the substrate-holding member being movable below the supply inlet; and

a temperature adjustment system which performs temperature adjustment for the substrate-holding member so that a temperature of the substrate-holding member is the same as

a temperature of the liquid to be supplied onto the substrate held by the substrate-holding member.

- 85. (New) The exposure apparatus according to claim 84, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that heat transfer is reduced between the substrate and the liquid on the substrate.
- 86. (New) The exposure apparatus according to claim 84, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that no temperature change of the liquid is caused by contact between the liquid and the substrate.
- 87. (New) The exposure apparatus according to claim 86, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that no temperature distribution is generated in the liquid.
- 88. (New) The exposure apparatus according to claim 86, further comprising a surface position-detecting unit which detects surface position information about a surface of the substrate by emitting a detecting light beam onto the substrate through the liquid and receiving a reflected light beam from the substrate through the liquid, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member to suppress measurement error of the surface position-detecting unit due to the temperature change of the liquid.
- 89. (New) The exposure apparatus according to claim 84, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that no temperature change of the substrate is caused by contact between the liquid and the substrate.
- 90. (New) The exposure apparatus according to claim 89, further comprising a mark-detecting system which detects an alignment mark on the substrate not through the

liquid, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that no temperature change of the substrate is caused by the contact between the liquid and the substrate after detecting the mark by the mark-detecting system.

- 91. (New) The exposure apparatus according to claim 84, wherein the temperature adjustment system uses a liquid which is the same as the liquid to be supplied onto the substrate to perform the temperature adjustment for the substrate-holding member.
- 92. (New) The exposure apparatus according to claim 84, further comprising a temperature sensor which measures a temperature of the substrate-holding member.
- 93. (New) The exposure apparatus according to claim 92, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that the measured temperature of the substrate-holding member is the same as the temperature of the liquid to be supplied onto the substrate held by the substrate-holding member.